

BRGBU2006SF

Rev.A Jun.-2016

描述 / Descriptions

GBU 塑封封装 超快恢复整流桥。

Ultrafast Recovery rectifier bridge in a GBU Plastic Package.

特征 / Features

采用玻璃钝化工艺生产的超快恢复整流桥，具有较低的反向漏电和高可靠性。

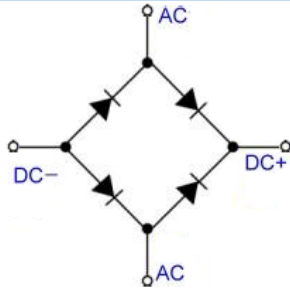
Glass passivated process to produce Ultrafast Recovery rectifier bridge ,with low reverse leakage current and high reliability.

用途 / Applications

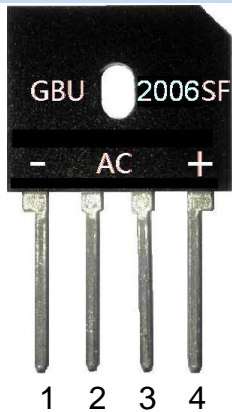
用于高频、高压、大电流整流二极管，续流二极管。

For high frequency, high voltage, high current rectifier diode, freewheeling diode.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1 : DC- PIN2 : AC PIN 3 : AC PIN 4 : DC+

放大及印章代码 / h_{FE} Classifications & Marking

见印章说明。 See Marking Instructions

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Peak Repetitive Reverse Voltage	V_{RRM}	600	V
Maximum RMS Voltage	V_{RMS}	420	V
Maximum DC Blocking Voltage	V_{DC}	600	V
Maximum Average Forward Current	$I_{(AV)}$	4×20	A
Peak forward surge current	I_{FSM}	180	A
Typical Thermal Resistance Junction to Case	$R_{\theta JC}$	2.2	°C/W
Junction Temperature Range	T_j	150	°C
Storage Temperature Range	T_{stg}	-55~150	°C

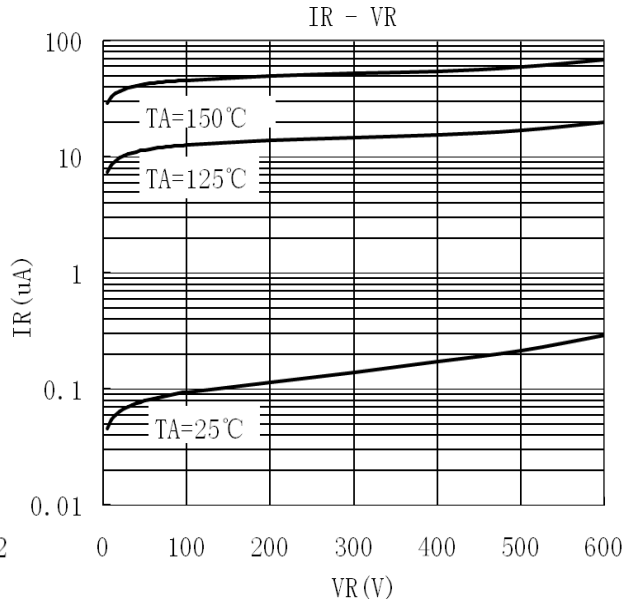
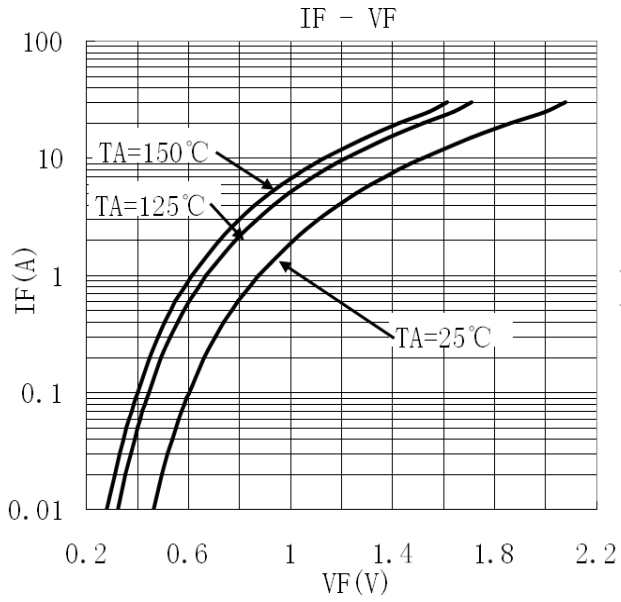
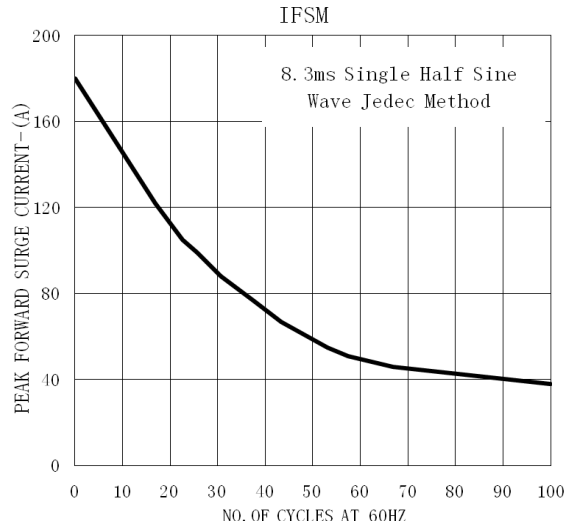
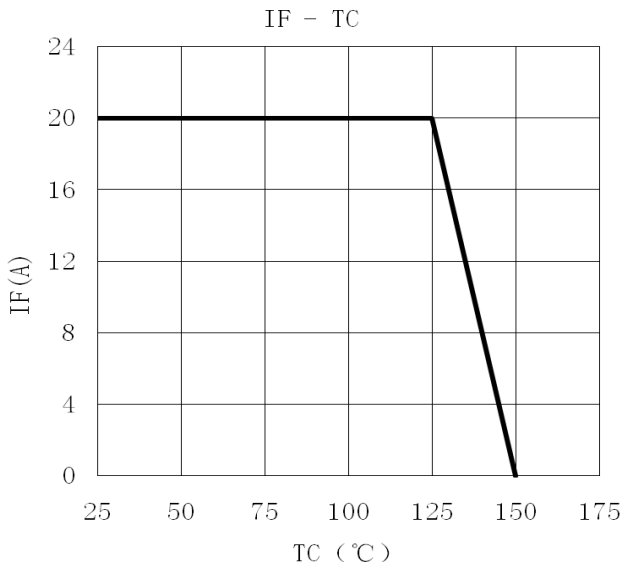
电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Reverse Voltage	V_R	$I_R=1mA$	600	680		V
Forward Voltage	V_F	$I_F=5A$ $T_C=25^\circ C$		1.28	1.45	V
		$I_F=5A$ $T_C=125^\circ C$		1.05	1.25	
		$I_F=10A$ $T_C=25^\circ C$		1.55	1.75	
		$I_F=10A$ $T_C=125^\circ C$		1.25	1.45	
		$I_F=20A$ $T_C=25^\circ C$		1.95	2.25	
		$I_F=20A$ $T_C=125^\circ C$		1.55	1.75	
Instantaneous Reverse Current	I_R (Note 1)	$V_R=600V$ $T_a=25^\circ C$			10	μA
		$V_R=600V$ $T_a=125^\circ C$			500	
Reverse Recovery Time	t_{rr}	$I_F=0.5A$ $I_R=1.0A$ $I_{RR}=0.25A$		35	50	ns

注/Notes:

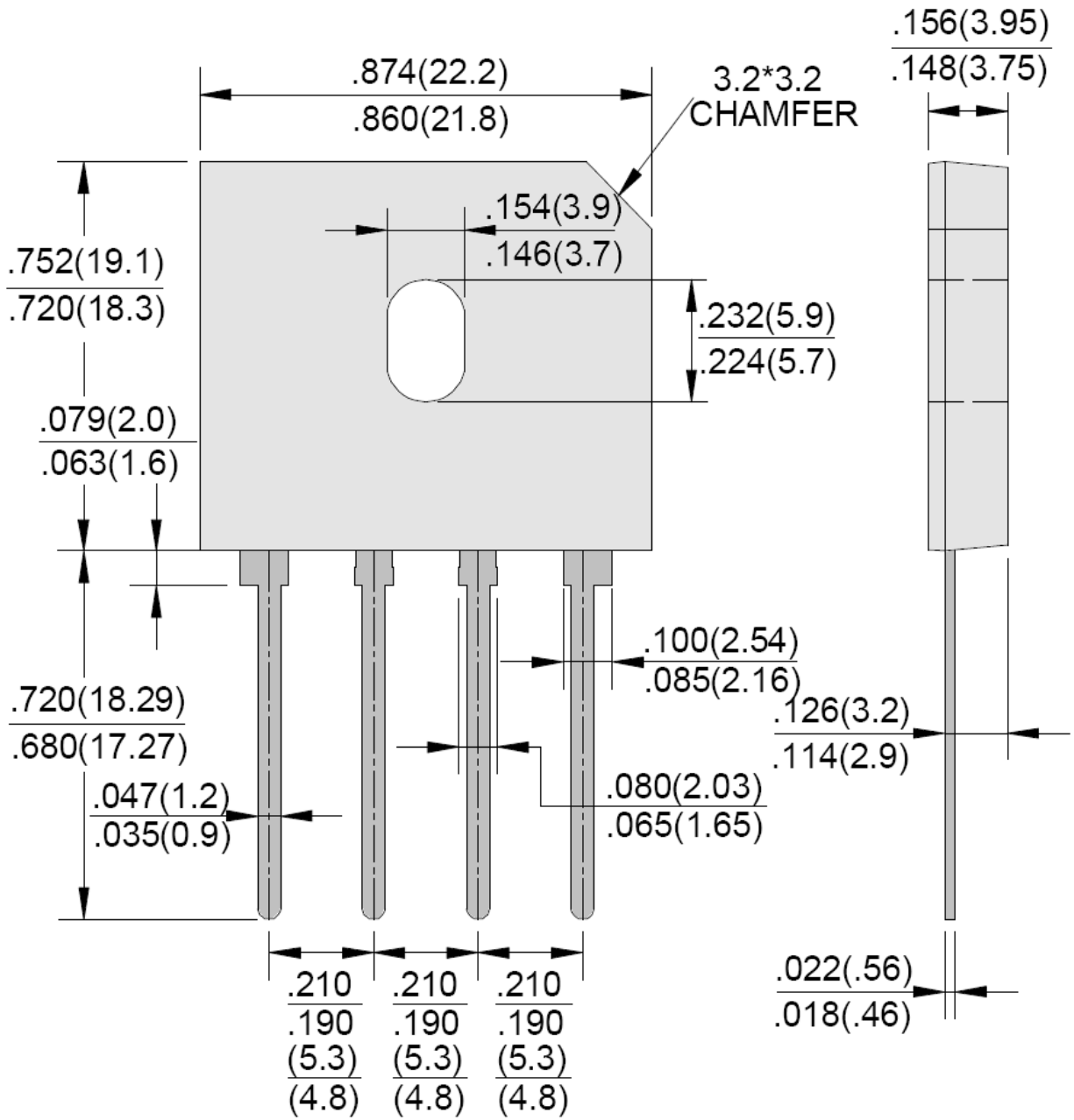
- 使用极短的测试时间,以尽量减少自热效应。/Short duration pulse test used to minimize self-heating effect.
- 除非特别注明,数值为一个芯片的参数。/ Unless otherwise noted, values for the parameters of a single chip

电参数曲线图 / Electrical Characteristic Curve



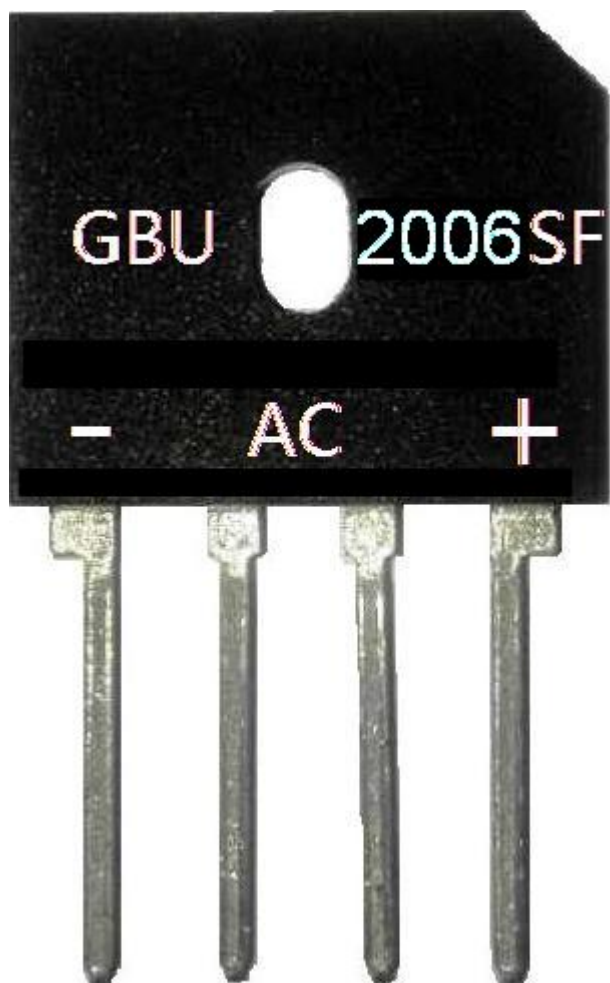
外形尺寸图 / Package Dimensions

GBU



Dimensions in inches and (millimeters)

印章说明 / Marking Instructions



说明：

GBU2006SF： 产品型号

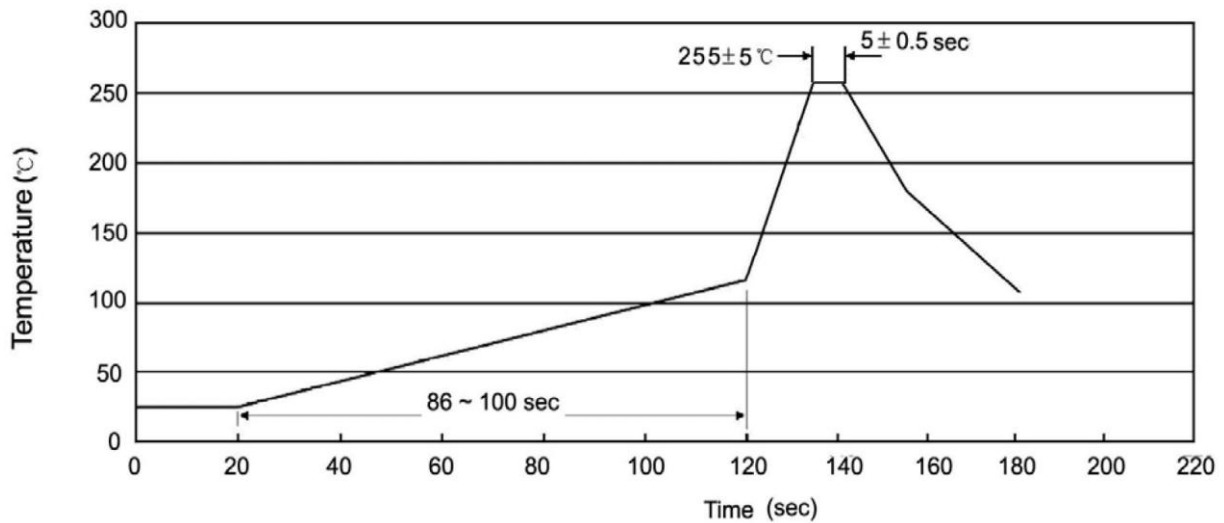
- AC +： 引脚功能

Note:

GBU2006SF： Product Type

- AC +： Pin function

波峰焊温度曲线图(无铅) / Temperature Profile for Dip Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 255±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：270±5°C

时间：10±1 sec.

Temp.:270±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

散件包装 / BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit : mm ³)		
	Units/Bag 只/袋	Bags/Inner Box 袋/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Bag 袋	Inner Box 盒	Outer Box 箱
GBU	-	-	500	10	5,000	-	203×203×44	445×215×260

使用说明 / Notices